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Kind regards,

Team Nexperia

BAT54XY

Schottky barrier quadruple diode

Rev. 3 — 8 October 2012 Product data sheet

1. Product profile

1.1 General description

Schottky barrier quadruple diode with an integrated guard ring for stress protection. Two electrically isolated dual Schottky barrier diodes series, encapsulated in a very small SOT363 (SC-88) Surface-Mounted Device (SMD) plastic package.

1.2 Features and benefits

- Low forward voltage
- Low capacitance
- AEC-Q101 qualified

1.3 Applications

- Ultra high-speed switching
- Line termination
- Voltage clamping
- Reverse polarity protection

1.4 Quick reference data

Table 1. Quick reference data

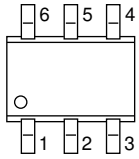
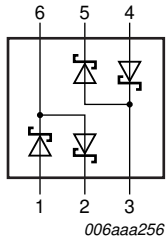
T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per diode							
V_R	reverse voltage			-	-	30	V
I_F	forward current			-	-	200	mA
V_F	forward voltage	I_F = 10 mA	[1]	-	-	400	mV

[1] Pulse test: $t_p \leq 30$ ms; $\delta \leq 0.02$.

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	anode 1		
2	cathode 2		
3	anode 3/cathode 4		
4	anode 4		
5	cathode 3		
6	cathode 1/anode 2		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BAT54XY	SC-88	plastic surface-mounted package; 6 leads	SOT363

4. Marking

Table 4. Marking codes

Type number	Marking code[1]
BAT54XY	*C5

[1] * = placeholder for manufacturing site code.

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per diode					
V_R	reverse voltage		-	30	V
I_F	forward current		-	200	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$	-	300	mA
I_{FSM}	non-repetitive peak forward current	$t_p < 10$ ms	-	600	mA
T_j	junction temperature		-	125	°C
T_{amb}	ambient temperature		−55	+125	°C
T_{stg}	storage temperature		−65	+150	°C

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point	in free air	[1]	-	-	260	K/W

[1] Soldering point at pins 2, 3, 5 and 6.

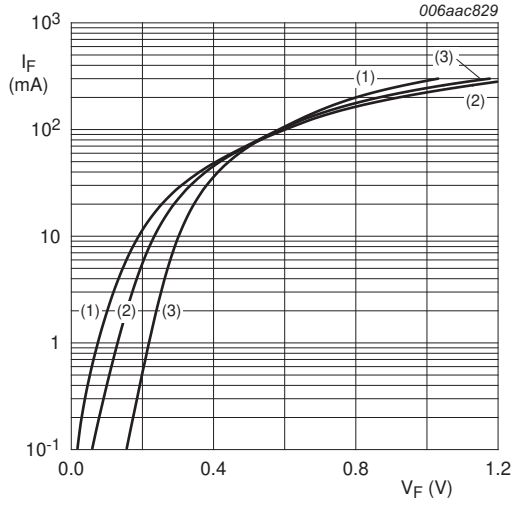
7. Characteristics

Table 7. Characteristics

T_{amb} = 25 °C unless otherwise specified.

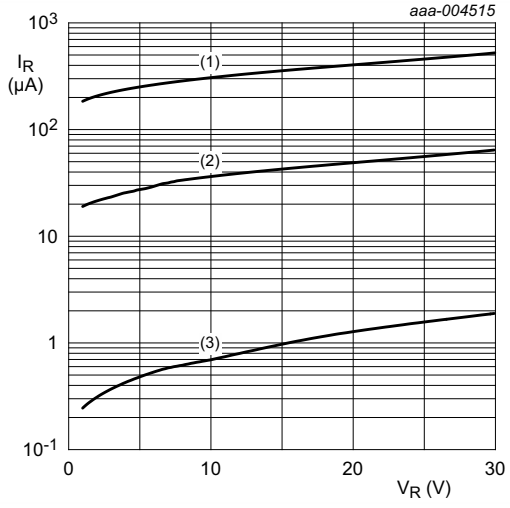
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per diode							
V_F	forward voltage		[1]				
		I_F = 0.1 mA		-	-	240	mV
		I_F = 1 mA		-	-	320	mV
		I_F = 10 mA		-	-	400	mV
		I_F = 30 mA		-	-	500	mV
		I_F = 100 mA		-	-	800	mV
I_R	reverse current	V_R = 25 V		-	-	2	µA
C_d	diode capacitance	V_R = 1 V; f = 1 MHz		-	-	10	pF

[1] Pulse test: $t_p \leq 300$ µs; $\delta \leq 0.02$.



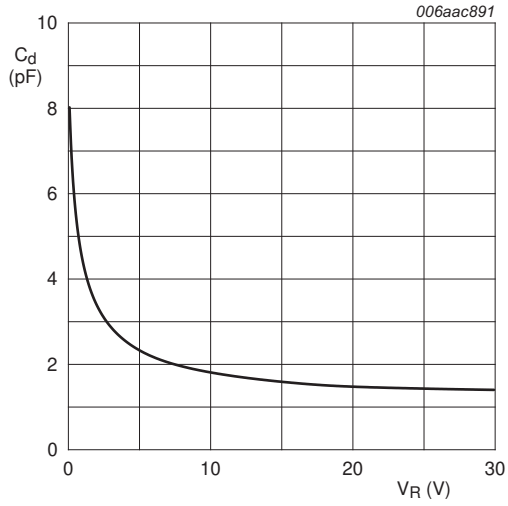
(1) T_{amb} = 125 °C
(2) T_{amb} = 85 °C
(3) T_{amb} = 25 °C

Fig 1. Forward current as a function of forward voltage; typical values



(1) T_{amb} = 125 °C
(2) T_{amb} = 85 °C
(3) T_{amb} = 25 °C

Fig 2. Reverse current as a function of reverse voltage; typical values



T_{amb} = 25 °C; f = 1 MHz

Fig 3. Diode capacitance as a function of reverse voltage; typical values

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline

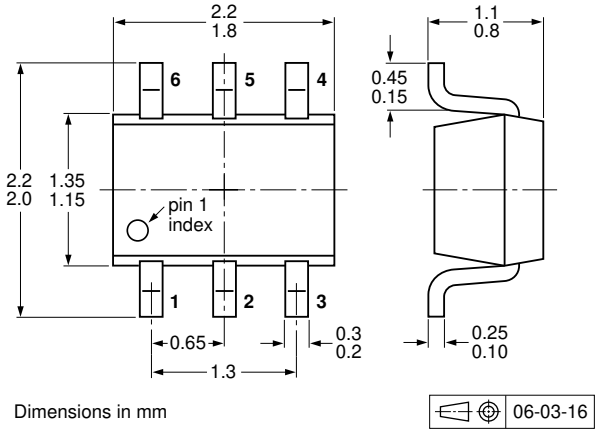


Fig 4. Package outline SOT363 (SC-88)

10. Packing information

Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number	Package	Description		Packing quantity	
				3000	10000
BAT54XY	SOT363	4 mm pitch, 8 mm tape and reel; T1	[2]	-115	-135
		4 mm pitch, 8 mm tape and reel; T2	[3]	-125	-165

[1] For further information and the availability of packing methods, see Section 14.

[2] T1: normal taping

[3] T2: reverse taping

11. Soldering

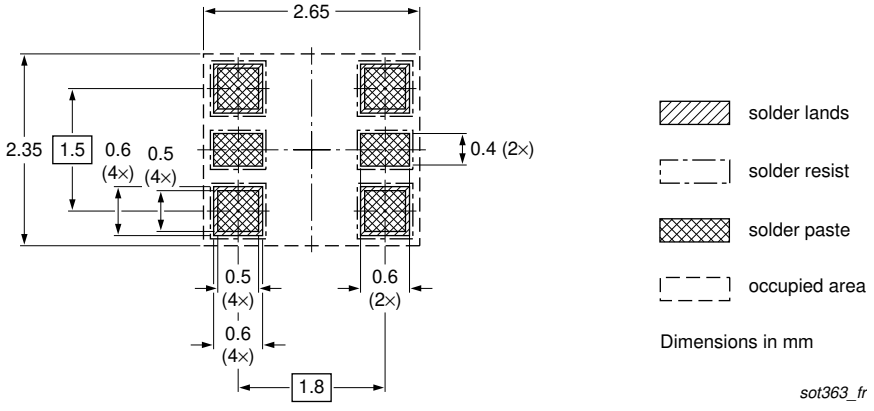


Fig 5. Reflow soldering footprint SOT363 (SC-88)

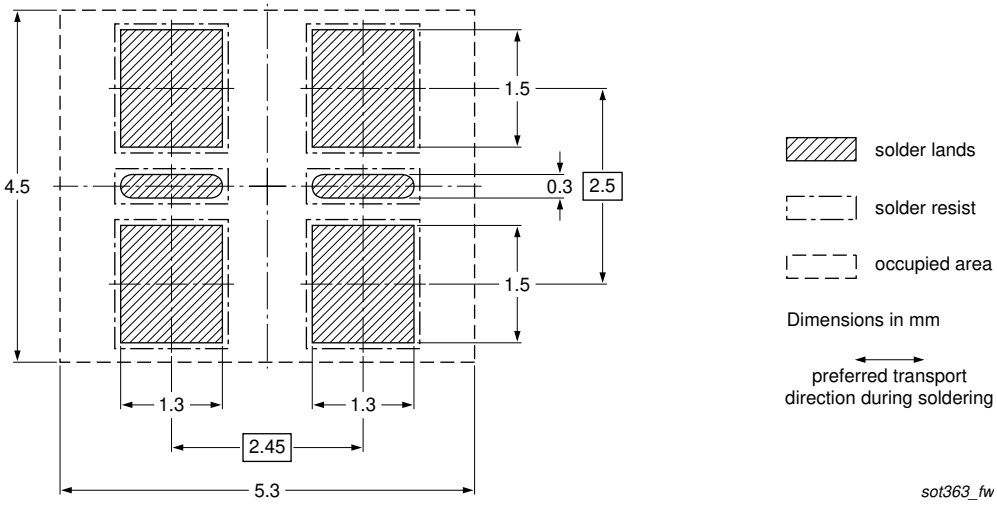


Fig 6. Wave soldering footprint SOT363 (SC-88)

12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAT54XY v.3	20121008	Product data sheet	-	BAT54XY v.2
Modifications:	• Section 1: updated • Section 4: updated • Table 7: updated • Figure 1 to 2: updated • Section 8 “Test information”: added • Figure 4: replaced by minimized package outline drawing • Section 11 “Soldering”: added • Section 13 “Legal information”: updated			
BAT54XY v.2	20100113	Product data sheet	-	BAT54XY v.1
BAT54XY v.1	20050117	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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15. Contents

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